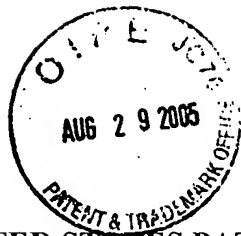


Docket No.: 067162-0021



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	Customer Number: 20277
	:	
Ryu MAKABE, et al.	:	Confirmation Number: 4281
	:	
Application No.: 10/662,276	:	Group Art Unit: 2813
	:	
Filed: September 16, 2003	:	Examiner: Tuan H. Nguyen
	:	

For: SEMICONDUCTOR WAFER, SEMICONDUCTOR CHIP AND DICING METHOD OF A SEMICONDUCTOR WAFER

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The following amendment and remarks are submitted in response to the non-final Office Action dated April 5, 2005.

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper. This listing of claims replaces all prior versions, and listings, of claims in the application.

Remarks begin on page 5 of this paper.